



Electronic Version 1.0.3

Stylesheet Version: 1.0

Submission Type: Information
Disclosure Statement

TRANSMITTAL FORM

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-shi Tae Heon Lee

SUBMITTED BY

Name: Mark B. Garred
Registration Number: 34,823
Electronic Signature Mark: /mbg/ Date Signed: 20030317

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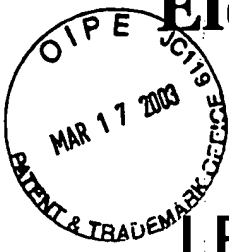
fee-transmittal

IDSfee.xml

us-information-disclosure-statement


IDSids.xml

Comments:



Electronic Information Disclosure Statement

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application: 
09/687048

Confirmation: 1120

Applicant(s): Kuri-shi Lee

Docket Number: AMKOR-052A

Group Art Unit: 2814

Examiner: Dilinh P. Nguyen

search string: 6498392 or 6464121 or 6452279 or 6444499 or 6400004 or 6395578 or 6384472 or 6380048 or 6373127 or 6339255 or 6326244 or 6323550 or 6316838 or 6309909 or 6303984 or 6297548 or 6294830 or 6291273 or 6291271 or 6285075 or 6282095 or 6281568 or 6281566 or 6256200 or 6239384 or 6229205 or 6225146 or 6222258 or 6218731 or 6211462 or 6208023 or 6208020 or 6204554 or 6201292 or 6201186 or 6198171 or 6197615 or 6184465 or 6181002 or 6177718 or 6169329 or 6140154 or 6133623 or 6130473 or 6130115 or 6118184 or 6118174 or 6100594 or 6087722 or 6081029).pn.

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03/20/2003 HLE333 00000014 194330 09687048
01 FC:1806 180.00 CH

Dilinh P. Nguyen 4/1/05

US Patent Documents



3/17/03

284

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 24716
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-Shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
Effective Receipt Date: 2003-03-17
Submission Type: Information Disclosure Statement
Filing Type: null
Confirmation Number: 1120
Attorney Docket Number: AMKOR-052A
Digital Certificate Holder: cn=Mark B. Garred, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US
Certificate Message Digest: ZXgkwJatUUiy2aFpbvfxuQ==



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Stylesheet Version: 1.0

Submission Type: Information
Disclosure Statement

Application Number: 09/687,048
Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-Shi Tae Leon Lee

SUBMITTED BY

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LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application: 
09/687048

Confirmation: 1120

Applicant(s): Kuri-Shi Lee

Docket
Number: AMKOR-052A

Group Art
Unit: 2814

Examiner: Dilinh P. Nguyen

search string: (6075284 or 6072228 or 6060769 or 6060768 or 6043430 or 6040626 or 6034423 or 6031279 or 6025640 or 6018189 or 6013947 or 6001671 or 5986885 or 5986333 or 5981314 or 5977615 or 5976912 or 5973388 or 5959356 or 5951305 or 5942794 or 5939779 or 5917242 or 5903050 or 5903049 or 5900676 or 5897339 or 5886398 or 5877043 or 5874784 or 5859471 or 5844306 or 5834830 or 5821615 or 5821457 or 5818105 or 5817540 or 5814884 or 5814883 or 5814881 or 5814877 or 5801440 or 5776798 or 5770888 or 5766972 or 5753977 or 5745984 or 5736432 or 5723899 or 5710064).pn.

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Dilinh P. Nguyen 4/1/05

US Patent Documents



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Disclosure Statement

Application Number: 09/687,048

Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-Shi Tae Heon Lee

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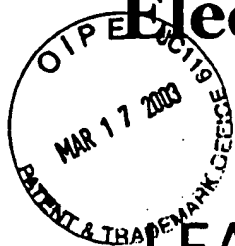
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LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

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09/687048

Confirmation: 1120

Applicant(s): Kuri-Shi Lee

Docket

AMKOR-052A

Number:

Group Art

2814

Unit:

Examiner:

Dilinh P. Nguyen

search string: (5703407 or 5696666 or 5689135 or 5683806 or 5673479 or 5665996 or 5650663 or 5646831 or 5644169 or 5641997 or 5640047 or 5639990 or 5633528 or 5625222 or 5608267 or 5604376 or 5594274 or 5592025 or 5581122 or 5545923 or 5544412 or 5543657 or 5539251 or 5534467 or 5517056 or 5508556 or 5493151 or 5474958 or 5454905 or 5444301 or 5435057 or 5424576 or 5414299 or 5410180 or 5406124 or 5391439 or 5343076 or 5336931 or 5335771 or 5332864 or 5327008 or 5294897 or 5279029 or 5277972 or 5273938 or 5266834 or 5258094 or 5252853 or 5250841 or 5221642).pn.

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Dilinh P. Nguyen 4/1/05

US Patent Documents

2814



3/17/03

Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 24718
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
Effective Receipt Date: 2003-03-17
Submission Type: Information Disclosure Statement
Filing Type: null
Confirmation Number: 1120
Attorney Docket Number: AMKOR-052A
Digital Certificate Holder: cn=Mark B. Garred, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US
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Stylesheet Version: 1.0

Submission Type: Information
Disclosure Statement

Application Number: 09/687,048

Attorney Docket Number: AMKOR-052A

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

First Named Inventor: Kuri-shi Tae Heon Lee

SUBMITTED BY

Name: Mark B. Garred
Registration Number: 34,823
Electronic Signature Mark: /mbg/ Date Signed: 20030317

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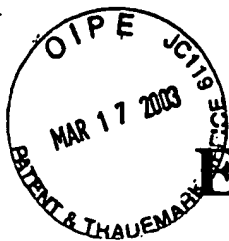
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Attached Files:

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Comments:



Electronic Information Disclosure Statement

LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH

Application: 
09/687048

Confirmation: 1120

Applicant(s): Kuri-shi Lee

Docket
Number: AMKOR-052A

Group Art
Unit: 2814

Examiner: Dilinh P. Nguyen

(5218231 or 5216278 or 5214845 or 5200809 or 5200362 or 5096852 or 5087961 or 5070039 or 5065223 or 5029386 or 4987475 or 4935803 or 4920074 or 4907067 or 4862246 or 4862245 or 4812896 or 4756080 or 4737839 or 4707724 or 4417266 or 4301464 or 4289922 or 4258381 or 4189342 or 4054238 or 3838984 or RE36907 or RE36613 or 20020140068 or 20020140061 or 20020024122 or 20020011654 or 20010008305).pn.

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Dilinh P. Nguyen 4/1/05

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents



3/17/03
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

2814 \$

#19
D. Scott
4/8/03

EFS ID: 24714
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
Effective Receipt Date: 2003-03-17
Submission Type: Information Disclosure Statement
Filing Type: null
Confirmation Number: 1120
Attorney Docket Number: AMKOR-052A
Digital Certificate Holder: cn=Mark B. Garred, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US
Certificate Message Digest: MpGX5uFIKcKaFBVLgmVfTA==
Total Fees Authorized: \$180.0
Payment Category: DA - Deposit Account
Deposit Account Number: 194330
Deposit Account Name: Mark B. Garred



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Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 24717
Application ID: 09687048
Title of Invention: LEADFRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED SOLDER JOINT STRENGTH
First Named Inventor: Kuri-Shi Lee
Domestic/Foreign Application: Domestic Application
Filing Date: 2000-10-13
Effective Receipt Date: 2003-03-17
Submission Type: Information Disclosure Statement
Filing Type: null
Confirmation Number: 1120
Attorney Docket Number: AMKOR-052A
Digital Certificate Holder: cn=Mark B. Garred, ou=Registered Attorneys, ou=Patent and Trademark Office, ou=Department of Commerce, o=U.S. Government, c=US
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Large Entity

TOTAL FEES AUTHORIZED: \$ 180

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Deposit Account Name: STETINA BRUNDA GARRED & BRUCKER



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Mark B. Garred

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Date Signed:

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ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Submission Of Information Disclosure Stmt Fee		1	1806	\$ 180	\$ 180

Subtotal For Additional Fees: \$ 180